

## FORM PTO-1449

## INFORMATION DISCLOSURE CITATION

Atty Docket  
END000008US1Serial No.  
To be assignedApplicant  
John U. Knickerbocker et al.Filing Date  
HerewithGroup Art Unit  
To be assigned

## U.S. PATENT DOCUMENTS

Examiner Initial		Document Number	Date	Name	Class	Sub-Class	Filing Date
CA	AA	5,962,133	10/99	Yamaguchi et al.			
WA	AB	5,834,140	11/98	Wolski et al.			
WA	AC	5,551,627	9/96	Leicht et al.			
WA	AD	5,215,645	6/93	DiFranco et al.			
WA	AE	4,478,883	10/84	Bupp et al.			
/	AF	/	/	/	/	/	/
/	AG	/	/	/	/	/	/
/	AH	/	/	/	/	/	/
/	AI	/	/	/	/	/	/
/	AJ	/	/	/	/	/	/
/	AK	/	/	/	/	/	/

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## FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Sub-Class	Translation
/	AL	/	/	/	/	/	Yes No
/	AM	/	/	/	/	/	Yes No
/	AN	/	/	/	/	/	Yes No
/	AO	/	/	/	/	/	Yes No
/	AP	/	/	/	/	/	Yes No

## OTHER (Including Author, Title, Date, Pertinent Pages, etc.)

CA	AR	Manko, Howard H., "Designing the Solder Joint," <u>Solders and Soldering: Materials, Design, Production, and Analysis for Reliable Bonding</u> , McGraw-Hill Book Company, New York, New York, 1964, pp. 123-139
WA	AS	Metfoils, Web page for EIS Circuit Supply, June 28, 2000
WA	AT	"Copper-Polymer Adhesion Process," <u>IBM Technical Disclosure Bulletin</u> , September 1987
WA	AU	"Plating Holes in Wired Circuit Boards," <u>IBM Technical Disclosure Bulletin</u> , May, 1980
	AV	"Rigid-Flexible Multilayer Boards," Dyconex Paper No. 3, 1997

Examiner

Date Considered

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP § 600. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant(s).